

[illegible]

WHAT IS CLAIMED IS:

1. A method of patterning a thin film comprising the steps of:

forming at least one strippable conductive film on a surface of a thin film to be patterned;

forming a mask on said at least one strippable conductive film;

patterning said thin film to be patterned by dry etching using said mask; and

removing said at least one strippable conductive film.

2. The method as claimed in claim 1, wherein said at least one strippable conductive film is a conductive organic film.

3. The method as claimed in claim 1, wherein said at least one strippable conductive film is an insulating organic film and a conductive film formed on said insulating organic film.

4. The method as claimed in claim 3, wherein said mask is formed by forming a resist film on said conductive film and then by patterning said resist film using an electron beam writing method.

5. The method as claimed in claim 3, wherein said conductive film is a metallic material film.

6. The method as claimed in claim 3, wherein said conductive film is a conductive organic film.

7. The method as claimed in claim 3, wherein said conductive film is a grounded film.

8. A method of manufacturing a thin-film device, at least a part of a thin-film pattern being fabricated by using a thin-film patterning method, said thin film patterning method comprising the steps of:

forming at least one strippable conductive film on a surface of a thin film to be patterned;

forming a mask on said at least one strippable conductive film;

patterning said thin film to be patterned by dry etching using said mask; and

removing said at least one strippable conductive film.

9. A method of manufacturing a thin-film magnetic head, at least a part of a thin-film pattern being fabricated by using a thin-film patterning method, said thin film patterning method comprising the steps of:

forming at least one strippable conductive film on a surface of a thin film to be patterned;

forming a mask on said at least one strippable
conductive film;

patterning said thin film to be patterned by dry
etching using said mask; and

removing said at least one strippable conductive film.

10. A method of patterning a thin film comprising the steps
of:

forming at least an insulating organic film and a
conductive film on a surface on which a resist pattern is to
be formed;

forming a resist film on said conductive film; and

patterning said resist film using an electron beam
writing method.

11. The method as claimed in claim 10, wherein said
conductive film is a metallic material film.

12. The method as claimed in claim 10, wherein said
conductive film is a conductive organic film.

13. The method as claimed in claim 10, wherein said
conductive film is a grounded film.

14. A method of manufacturing a thin-film device, at least

a part of a thin-film pattern being fabricated by using a thin-film patterning method, said thin film patterning method comprising the steps of:

forming at least an insulating organic film and a conductive film on a surface on which a resist pattern is to be formed;

forming a resist film on said conductive film; and patterning said resist film using an electron beam writing method.

15. A method of manufacturing a thin-film magnetic head, at least a part of a thin-film pattern being fabricated by using a thin-film patterning method, said thin film patterning method comprising the steps of:

forming at least an insulating organic film and a conductive film on a surface on which a resist pattern is to be formed;

forming a resist film on said conductive film; and patterning said resist film using an electron beam writing method.

16. A method of patterning a thin film comprising the steps of:

forming at least an insulating organic film and a conductive film on a surface of a thin film to be patterned;

forming a resist film on said conductive film;
patterning said resist film using an electron beam
writing method;

patterning said thin film to be patterned by dry
etching using said patterned resist film as a mask; and

removing said at least insulating organic film and
conductive film.

17. The method as claimed in claim 16, wherein said
conductive film is a metallic material film.

18. The method as claimed in claim 16, wherein said
conductive film is a conductive organic film.

19. The method as claimed in claim 16, wherein said
conductive film is a grounded film.

20. A method of manufacturing a thin-film device, at least
a part of a thin-film pattern being fabricated by using a
thin-film patterning method, said thin film patterning method
comprising the steps of:

forming at least an insulating organic film and a
conductive film on a surface of a thin film to be patterned;

forming a resist film on said conductive film;

patterning said resist film using an electron beam

writing method;

patterning said thin film to be patterned by dry etching using said patterned resist film as a mask; and removing said at least insulating organic film and conductive film.

21. A method of manufacturing a thin-film magnetic head, at least a part of a thin-film pattern being fabricated by using a thin-film patterning method, said thin film patterning method comprising the steps of:

forming at least an insulating organic film and a conductive film on a surface of a thin film to be patterned;

forming a resist film on said conductive film;

patterning said resist film using an electron beam writing method;

patterning said thin film to be patterned by dry etching using said patterned resist film as a mask; and

removing said at least insulating organic film and conductive film.